

(0,80 mm) .0315"

QRF8 SERIES

SLIM BODY GROUND PLANE SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?QRF8

- Insulator Material:** Black LCP
- Contact Material:** BeCu
- Ground Plane Material:** Phosphor Bronze
- Plating:** Au or Sn over 50µ" (1,27 µm) Ni
- Current Rating:** Contact: 2.2 A per pin (1 pin powered per row) Ground Plane: 8.5 A per ground plane (1 ground plane powered)
- Operating Temp Range:** -55°C to +125°C
- Voltage Rating:** 215 VAC
- RoHS Compliant:** Yes

Processing:

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0,10 mm) .004" max (018-026) (0,15 mm) .006" max (036-078)

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



MATED HEIGHT*			
QRF8 LEAD STYLE	QRM8 LEAD STYLE		
	-02.0	-05.0	-07.0
-05.0	(7,00) .276	(10,00) .394	(12,00) .472
-07.0	(9,00) .354	(12,00) .472	(14,00) .551

*Processing conditions will affect mated height.

ALSO AVAILABLE (MOQ Required)

- Other platings Contact Samtec.

Note: Patented

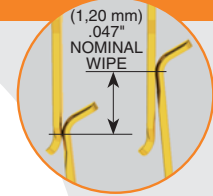
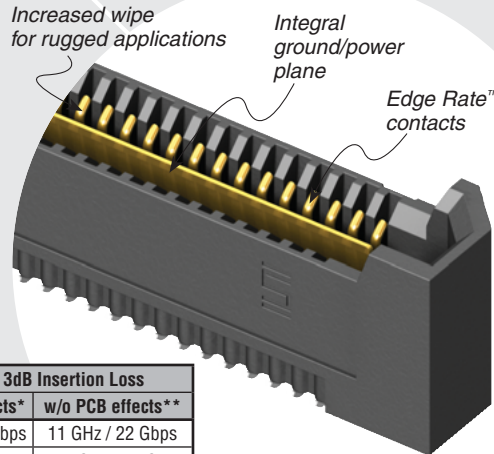
Note: Some lengths, styles and options are non-standard, non-returnable.

Board Mates: QRM8, EQRD



QRM8/QRF8 7 mm Stack Height	Type	Rated @ 3dB Insertion Loss	
		with PCB effects*	w/o PCB effects**
Single-Ended Signaling	-D	9.5 GHz / 19 Gbps	11 GHz / 22 Gbps
Differential Pair Signaling	-D	8.5 GHz / 17 Gbps	10.5 GHz / 21 Gbps
Differential Pair Signaling	-DP	9 GHz / 18 Gbps	—

*Performance data includes effects of a non-optimized PCB.
**Test board losses de-embedded from performance data.
Performance data for other stack heights and complete test data available at www.samtec.com?QRF8 or contact sig@samtec.com



Protocols Supported

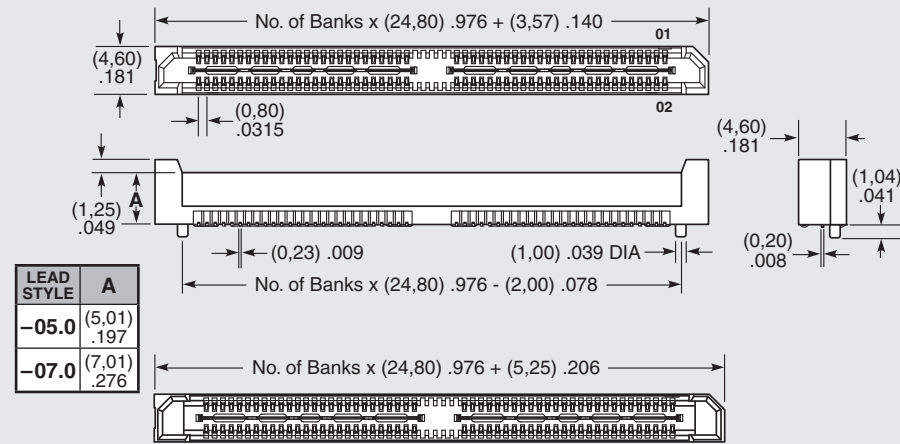
100 GbE

Download app notes at www.samtec.com/appnote
Contact SIG @ samtec.com for questions on protocols



28+ Gbps

QRF8	PINS PER ROW NO. OF PAIRS	LEAD STYLE	PLATING OPTION	TYPE	A	OTHER OPTION
	-026, -052, -078 (52 total pins per bank = -D) -018, -036, -054 (18 pairs per bank = -D-DP)	-05.0 = 5 mm Body Height -07.0 = 7 mm Body Height	-L = 10 µ" (0,25 µm) Gold on contact, Matte Tin on tail	-D = Single-Ended -D-DP = Differential Pair		-GP = Guide Post (Requires -GP on mating connector) -K = (5,00 mm) .197" DIA Polyimide Film Pick & Place Pad -TR = Tape & Reel (-018, -026, -036, -052 only)



LEAD STYLE	A
-05.0	(5,01) .197
-07.0	(7,01) .276

- Edge Rate™ contacts
- Increased contact wipe
- 10 year MFG
- Guide post option